

無鉛
LEAD FREE



15	33.3	32.1	28	53324-156*	53324-***6*
14	31.3	30.1	26	-146*	
13	29.3	28.1	24	-136*	
12	27.3	26.1	22	-126*	
11	25.3	24.1	20	-116*	
10	23.3	22.1	18	-106*	
9	21.3	20.1	16	-096*	
8	19.3	18.1	14	-086*	
7	17.3	16.1	12	-076*	
6	15.3	14.1	10	-066*	
5	13.3	12.1	8	-056*	
4	11.3	10.1	6	-046*	
3	9.3	8.1	4	-036*	
2	7.3	6.1	2	53324-026*	
標数 C K T.	C	B	A	4. MATERIAL NO.	

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		RELEASED ECNN0-J2003-2361 DRWN: A.IDA 03/03/13 CHK: J.MIYAZAWA 03/03/13 APPR: YO.ITO 03/03/13		DESCRIPTION MATERIAL 材料 注記参照 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 5-1		DESIGN UNITS ☒ mm ☐ INCH		THIRD ANGLE PROJECTION 		☐ mm INCH ☐ mm mm ONLY ☒		REVISE ON CAD ONLY	
										FINISH 仕上り — # —		10 UNDER 未満 ±0.2		DRAWN BY & DATE A. Ida 03/03/13		TITLE: 2.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)							
												10 OVER 以上 30 UNDER 未満 ±0.25		CHECKED BY & DATE J. Miyazawa 03/03/13									
												30 OVER 以上 ±0.3		APPROVED BY & DATE Y.Ito 03/03/13		MOLEX INCORPORATED							
										WIRE RANGE 適用電線範囲 — # —		ANGLE 角度 ±3°		CAD FILENAME SD-53324-003.S01		MATERIAL NO. SEE CHART		DRAWING NO. SD-53324-003		SHEET NO. 1 OF 1			
						0		REV INS. RANGE 被覆外径 — # —						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B							